



Material Content Data Sheet



Sales Product Name	TLF80511EJ V33			Issued		1. August 2018		
MA#	MA001730852							
Package	PG-DSO-8-52			Weight*		83.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.094	1.31	1.31	13072	13072
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8694	
	non noble metal	copper	7440-50-8	29.548	35.30	36.22	353024	362262
wire	non noble metal	copper	7440-50-8	0.039	0.05	0.05	461	461
encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1204	
	plastics	epoxy resin	-	4.637	5.54		55406	
	inorganic material	silicondioxide	60676-86-0	45.668	54.55	60.21	545627	602237
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8305	8305
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8656	8656
glue	plastics	epoxy resin	-	0.105	0.13		1252	
	noble metal	silver	7440-22-4	0.314	0.38	0.51	3755	5007
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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